

**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. When strikethrough cannot easily be perceived, or when five or fewer characters are deleted, [[double brackets]] are used to show the deletion. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please AMEND claims 1, 10 and 12 and ADD new claims 17-18 in accordance with the following:

1. (CURRENTLY AMENDED) A mold releasing film for printed circuit board production, which comprises a resin layer (P) having a thickness of 10-100  $\mu$ m, containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more.
2. (ORIGINAL) The mold releasing film for printed circuit board production according to claim 1, wherein the resin layer (P) further contains (B) a liquid crystalline polyester in an amount of 0.5 to 50 parts by weight per 100 parts by weight of the total weight of components (A) and (B).
3. (PREVIOUSLY PRESENTED) The mold releasing film for printed circuit board production according to claim 2, wherein the resin layer (P) further contains (C) a compound containing a monovalent, divalent, trivalent or tetravalent metal, in an amount of 0.1 to 10 parts by weight per 100 parts by weight of the total weight of components (A) and (B).
4. (PREVIOUSLY PRESENTED) The mold releasing film for printed circuit board production according to claim 3, wherein the monovalent, divalent, trivalent or tetravalent metal comprises at least one of divalent Zn and divalent Mg.
5. (ORIGINAL) The mold releasing film for printed circuit board production according to claim 2, wherein the resin layer (P) further contains (D) a silane compound in an amount of 0.1 to 5 parts by weight per 100 parts by weight of the total weight of components (A) and (B).
6. (ORIGINAL) The mold releasing film for printed circuit board production according to claim 5, wherein the silane compound (D) has an amino group.

7. (ORIGINAL) The mold releasing film for printed circuit board production according to claim 6, wherein the resin layer (P) further contains (E) a hydrocarbon-based wax in an amount of 0.1 to 4 parts by weight per 100 parts by weight of the total weight of components (A) and (B).

8. (ORIGINAL) The mold releasing film for printed circuit board production according to claim 1, which has a monolayer structure consisting essentially of the resin layer (P).

9. (CANCELED)

10. (CURRENTLY AMENDED) The mold releasing film for printed circuit board production according to claim ~~9~~17, wherein the elastomer (F) is (G) a partially hydrogenated polymer of a block copolymer of an aromatic vinyl compound and a conjugated diene compound.

11. (ORIGINAL) The mold releasing film for printed circuit board production according to claim 10, wherein the content of a bonded aromatic vinyl compound in component (G) is from 5 wt% to 65 wt%.

12. (CURRENTLY AMENDED) The mold releasing film for printed circuit board production according to claim ~~9~~17, wherein the elastomer (F) is (H) a copolymer of ethylene and a vinyl ester compound.

13. (PREVIOUSLY PRESENTED) The mold releasing film for printed circuit board production according to claim 1, obtained by molding through an extrusion tubular method.

14. (PREVIOUSLY PRESENTED) The mold releasing film for printed circuit board production according to claim 1, obtained by molding through a T-die extrusion method.

15. (PREVIOUSLY PRESENTED) The mold releasing film for printed circuit board production according to claim 1, having a contact angle between the film surface of its outermost surface layer and a water drop of 80° or more.

16. (PREVIOUSLY PRESENTED) The mold releasing film for printed circuit board production according to claim 1, wherein the printed circuit board is a flexible printed circuit board.

17. (NEW CLAIM) A mold releasing film for printed circuit board production, which has a multilayer structure comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more and a layer (Q) containing (F) an elastomer.

18. (NEW CLAIM) A method for producing a printed circuit board comprising hot-pressing a copper-clad laminate or a copper foil and a prepreg or a heat-resistant film along with a mold-releasing film,

wherein the mold releasing film is a film comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more.